



*materials*



an Open Access Journal by MDPI

## Low k Dielectric Materials

Guest Editor:

### **Prof. Dr. Rajendra Singh**

The Holcombe Department of  
Electrical and Computer  
Engineering, Clemson University,  
105 Riggs Hall, Room 206,  
Clemson, SC 29634, USA

Deadline for manuscript  
submissions:

**closed (30 June 2012)**

### **Message from the Guest Editor**

Dear Colleagues,

For Low k dielectric materials, the value of dielectric constant is less than the dielectric constant of silicon dioxide. Such materials are of great importance for multi-level interconnections of nanoelectronics and radio frequency (RF) devices and circuits. Other applications include optoelectronics, 3-D integrated circuits, microelectromechanical systems (MEMS), nanoelectromechanical (NEMS), sensors and detectors and packaging of various types of devices and circuits. All topics related to synthesis, and properties of low-k dielectrics, various processing techniques, process integration, performance and reliability of low-K based devices, circuits and systems are of interest for this journal issue.

Dr. Rajendra Singh  
*Guest Editor*



[mdpi.com/si/1173](http://mdpi.com/si/1173)

**Special** issue



an Open Access Journal by MDPI

## Editor-in-Chief

### Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

## Message from the Editor-in-Chief

*Materials* (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

## Author Benefits

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.

**High Visibility:** indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.

**Journal Rank:** JCR - Q1 (Metallurgy and Metallurgical Engineering) / CiteScore - Q2 (*Condensed Matter Physics*)

## Contact Us

Materials Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland

Tel: +41 61 683 77 34  
[www.mdpi.com](http://www.mdpi.com)

[mdpi.com/journal/materials](http://mdpi.com/journal/materials)  
[materials@mdpi.com](mailto:materials@mdpi.com)  
[X@Materials\\_Mdpi](https://twitter.com/Materials_Mdpi)